ABSTRACT OF THE DISCLOSURE

The present invention relates to a process for melting and adhering material to produce three-dimensional objects by means of selective heating via microwave radiation. Unlike selective laser sintering, the present process uses simple microwave radiation commonly available in any household. The selectivity of heating is achieved by applying one or more susceptors to selected regions of a layer composed of a pulverulent substrate, and then heating the susceptor by means of microwave radiation. The heated susceptor transfers the energy present therein to a pulverulent substrate surrounding the susceptor, and the substrate is thereby melted, providing firm adhesion within the substrate after cooling.